



INFORMATION DISCLOSURE STATEMENT BY APPLICANTS PTO FORM 1449	Atty. Docket No. 10191/3165	Serial No. 10/614,540
	Applicant(s) SIEGLE et al.	
	Filing Date July 7, 2003	Group 2561

U. S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NUMBER	PATENT DATE	NAME	CLASS	SUBCLASS	FILING DATE
PD	2001/0055775	Dec. 27, 2001	Schultz et al.	—	—	—
PD	4,670,088	June 2, 1987	Tsaur et al.	—	—	—

FOREIGN PATENT DOCUMENTS

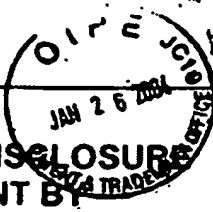
EXAMINER'S INITIALS	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB-CLASS	TRANSLATION	
						YES	NO
PD	WO 00/79298	Dec. 28, 2000	PCT	—	—	NA	

OTHER DOCUMENTS

EXAMINER'S INITIALS	AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.

EXAMINER	PHUC T. DANG	DATE CONSIDERED	6/15/05
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PD	1007 46 58	March 17, 1998	Japan	—	—	* abstract	

OTHER DOCUMENTS

EXAMINER'S INITIALS	AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.
PD	Lee K et al., "Enhanced tunneling magnetoresistance and thermal stability of magnetic tunnel junction by rapid thermal anneal", JOURNAL OF MAGNETISM AND MAGNETIC MATERIALS, ELSEVIER, AMSTRDAM, NL., Bd. 239, Nr. 1-3, 02/2002, S. 120-122, XP-004351733.
PD	Wu et al., "Thermal annealin study of spin valves", JOURNAL OF APPLIED PHYSICS, Bd. 89, Nr. 01-06-11, S.7616-7618, XP-001072884.

EXAMINER

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